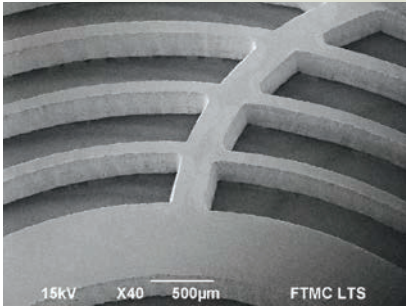


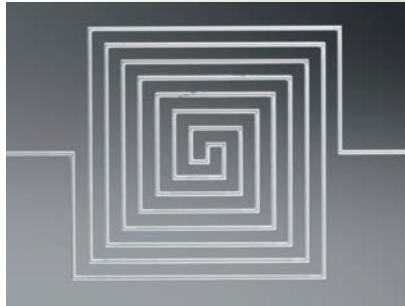
Material processing samples

GLASS MILLING



Fused-silica milling. Stripe width 100 µm, thickness 250 µm.

GLASS MILLING



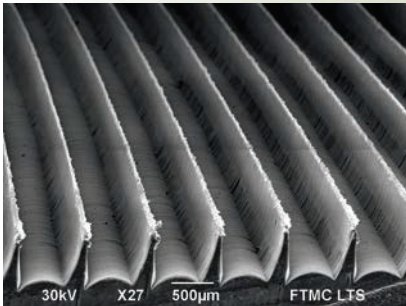
Soda-lime milling. 330 µm width channels.

POLYIMIDE CUTTING



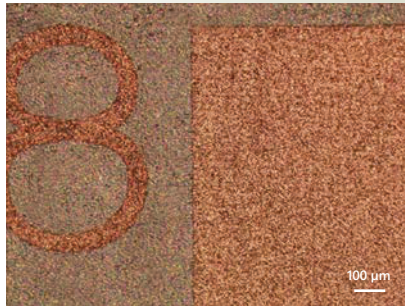
Polyimide cutting. Smallest features down to 165 µm.

TEFLON MILLING



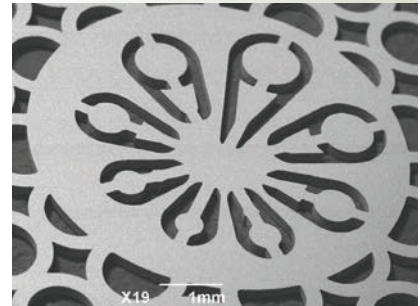
Teflon (PTFE) ablation. Courtesy of FTMC.

PCB ABLATION



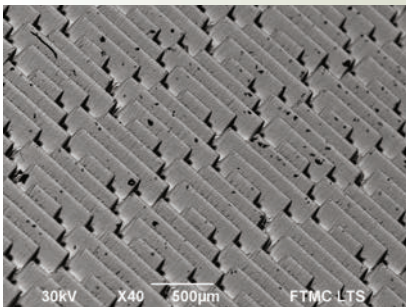
Clear insulation layer removal from flexible PCB. Courtesy of FTMC.

STAINLESS STEEL CUTTING



Stainless steel cutting. Smallest features down to 150 µm.

SURFACE STRUCTURING



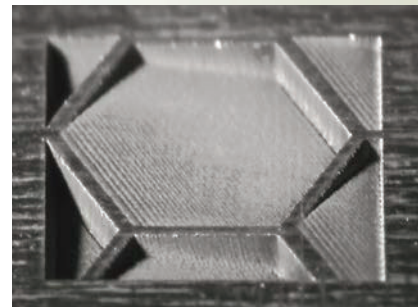
"Shark skin" surface structuring. Courtesy of FTMC.

STAINLESS STEEL MARKING



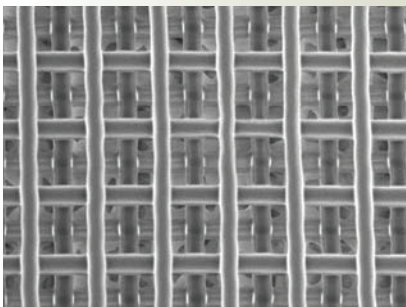
Highly resistant stainless steel black marking.

COPPER ABLATION



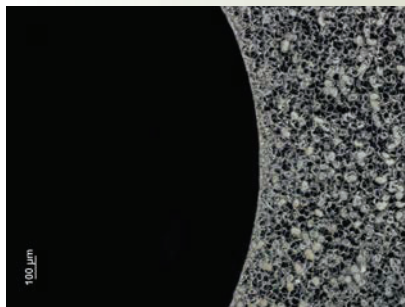
Surface roughness of 0.2 µm. Courtesy of Leibnitz IOM.

PHOTOPOLYMERIZATION



Courtesy of Workshop of Photonics.

SILICON CUTTING



Crystalline silicon processing.

COPPER DEEP 3D ENGRAVING



Courtesy of FTMC.